

PATENTS



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Takeo MATSUKI et al.

Confirmation No. 4114

Serial No. 09/764,880

GROUP 2818

Filed January 23, 2001

Examiner Thinh T. Nguyen

SEMICONDUCTOR DEVICE STRUCTURE  
AND METHOD FOR MANUFACTURING THE  
SAME

AMENDMENT

Commissioner for Patents

Washington, D.C. 20231

Sir:

Responsive to the Official Action of April 1, 2002,  
please amend the above-identified application as follows

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TECHNOLOGY CENTER 2800

11/B  
P. Walker  
88-02

IN THE CLAIMS:

Amend claim 1 as follows:

--1. (amended) A structure for a semiconductor device,  
provided with a contact plug, which is formed by forming a  
contact hole through a first interlayer insulating film on a  
silicon substrate and by filling the contact hole with silicon,  
comprising:

a silicide pad formed on the top surface of the silicon  
contact plug in a self-aligning manner with said silicon contact  
plug and having a diameter which is larger than that of the  
silicon contact plug;

B1  
cont'd